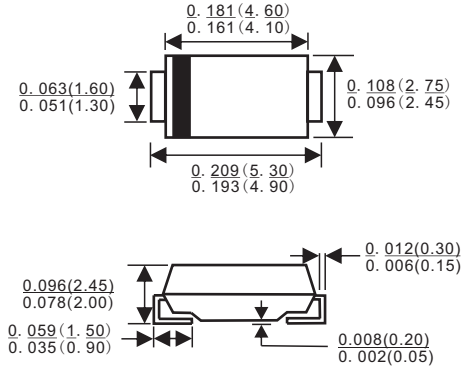




### SMA/DO-214AC

### Features

- ✧ Glass passivated junction chip
- ✧ For surface mounted application
- ✧ Low profile package
- ✧ Built-in strain relief
- ✧ Ideal for automated placement
- ✧ Easy pick and place
- ✧ Ultrafast recovery time for high efficiency
- ✧ Low forward voltage, low power loss
- ✧ High temperature soldering guaranteed: 260°C/10 seconds on terminals
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V0



### Mechanical Data

- ✧ Cases: Molded plastic
- ✧ Polarity: Indicated by cathode band
- ✧ Weight: 0.064 gram

Dimensions in inches and(millimeters)

### Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	US1A	US1B	US1D	US1G	US1J	US1K	US1M	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_L=110^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method )	$I_{FSM}$	30							A
Maximum Instantaneous Forward Voltage @ 1.0A	$V_F$	1.0			1.7			V	
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	$I_R$	5.0				150			uA uA
Maximum Reverse Recovery Time ( Note 1 )	$T_{rr}$	50			75			nS	
Typical Junction Capacitance ( Note 2 )	$C_j$	15			10			pF	
Maximum Thermal Resistance (Note 3)	$R_{\theta JA}$ $R_{\theta JL}$	75				27			$^\circ\text{C/W}$
Operating Temperature Range	$T_J$	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to + 150							$^\circ\text{C}$

- Notes:
1. Reverse Recovery Test Conditions:  $I_F=0.5A$ ,  $I_R=1.0A$ ,  $I_{RR}=0.25A$
  2. Measured at 1 MHz and Applied  $V_R=4.0$  Volts
  3. P.C.B. Mounted on 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Area.

### RATINGS AND CHARACTERISTIC CURVES (US1A THRU US1M)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

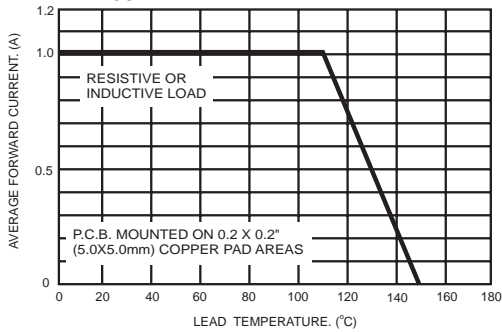


FIG.2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

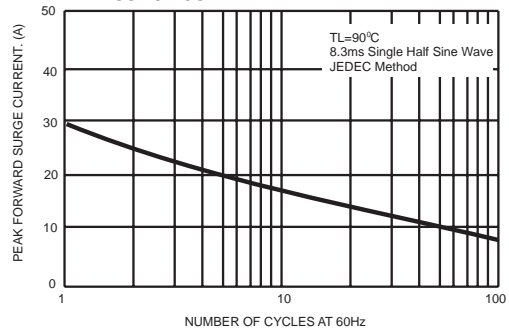


FIG.3- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

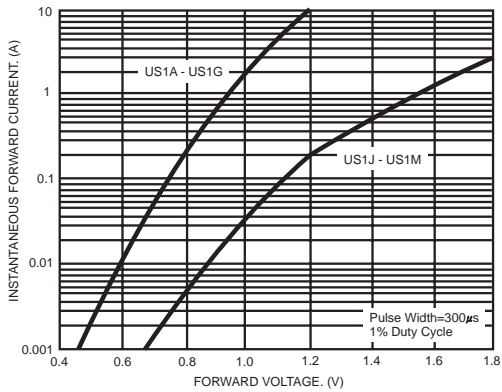


FIG.4- TYPICAL REVERSE CHARACTERISTICS

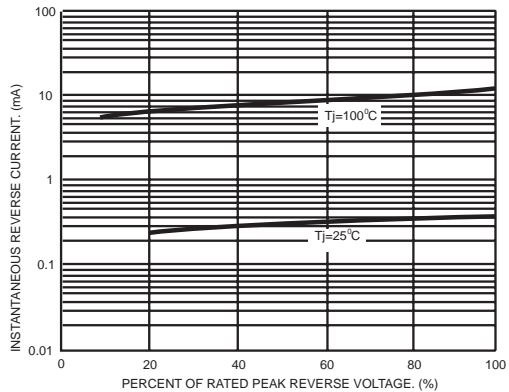


FIG.5- TYPICAL JUNCTION CAPACITANCE

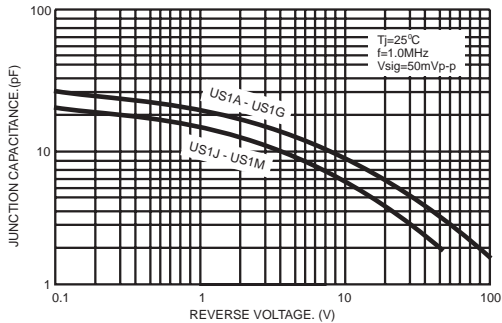


FIG.6- TYPICAL TRANSIENT THERMAL IMPEDANCE

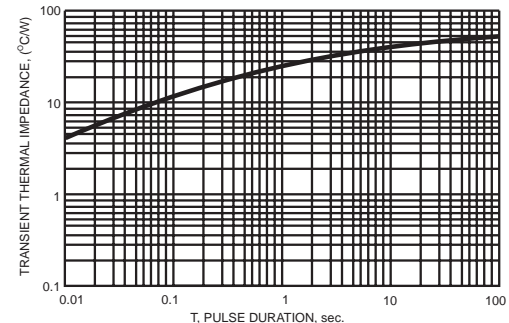
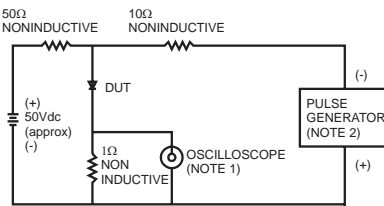
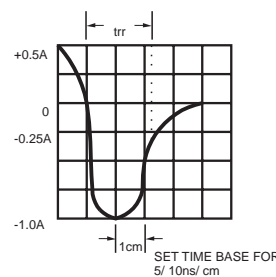


FIG.7- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance=1 megohm 22pf  
2. Rise Time=10ns max. Source Impedance=50 ohms



PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
SMA	5000/REEL	80000	36X30.6X31	12.00	11.00